	512000.0				/			
Title: Datasheet for LM5088, LM5088-Q1 and LM25088, LM25088-Q1								
Customer Contact: PCN Manager Dept: Quality Services								
Change Type:			•		•			
Assembly Site	Desid	ın			Wafer Bump Site			
Assembly Process	_	Sheet			Wafer Bump Material			
Assembly Materials	Part	number change			Wafer Bump Process			
Mechanical Specification	Test				Wafer Fab Site			
Packing/Shipping/Labeling	Test	Process			Wafer Fab Materials			
					Wafer Fab Process			
Notification Details								
Description of Change:								
Texas Instruments Incorporated is a	nnounci	ng an information o	nlv	no	tification.			
The product datasheet(s) is being u								
The following change history provid								
••-								
TEXAS					LM5088, LM5088-Q1			
Instruments			SNVS60)0J -	- DECEMBER 2008 - REVISED JUNE 2022			
Changes from Revision I (August 2014) to Revis	on J (June 2022)			Page			
 Updated the numbering format for table 	les, figures	and cross-references t	throu	gho	out the document1			
 Updated AEC-Q100 bullet to the lates 								
Corrected grammar throughout docum								
Added EP as pin 17 Changed all instances of legacy terminates.								
 Changed all instances of legacy terming Moved storage temperature from ESD 								
Changed unit and value from kV to V i								
Changed Handling Ratings to ESD Ra								
 Moved storage temperature to Absolute 	te Maximu	n Ratings			5			
 Added new ESD ratings table for LM5 								
 Added application and implementation 	note			••••	21			
No.								
IEXAS INSTRUMENTS					LM25088, LM25088-Q1			
INSTRUMENTS			SNVS6	09K	- DECEMBER 2008 - REVISED JUNE 2022			
Changes from Revision J (January 2015) to Revision K (May 2022) Page								
 Updated the numbering format for tall 	oles, figure	s, and cross-references	thro	ugl	hout the document1			
Corrected grammar throughout document								
Updated AEC-Q100 bullet to latest standard								
Added EP as pin 17								
Changed all instances of legacy terminology to controller								
table								
Added new ESD Ratings Table for LM25088-Q1								
The datasheet number will be changed	ging.	-						
Device Family		Change From:		\perp	Change To:			
LM5088, LM5088-Q1		SNVS600I			SNVS600J			
23000, 23000 Q1		311130001		+	211120003			
LM25088, LM25088-Q1		SNVS609J			SNVS609K			

These changes may be reviewed at the datasheet links provided.

https://www.ti.com/product/LM5088 https://www.ti.com/product/LM25088

Error! Bookmark not defined.

Reason for Change:

To accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

Changes to product identification resulting from this notification:

None.

Product Affected:

LM5088MH-1/NOPB	LM5088MH-2/NOPB	LM5088MHX-1/NOPB	LM5088MHX-2/NOPB
LM5088QMH-1/NOPB	LM5088QMH-2/NOPB	LM5088QMHX-1/NOPB	LM5088QMHX-2/NOPB
LM25088MH-1/NOPB	LM25088MH-2/NOPB	LM25088MHX-1/NOPB	LM25088MHX-2/NOPB
LM25088QMH-1/NOPB	LM25088QMH-2/NOPB	LM25088QMHX-1/NOPB	LM25088QMHX-2/NOPB

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Location	E-Mail	
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Notification# 20220612000.0